



# Product Change Notification

**Change Notification #:** 115500 - 00

**Change Title:** Intel® Server Systems  
E1208WTTGCNC, E2224WTTGCS  
and E2312WTTGCS  
PCN 115500-00, Product Design,  
Replacing BMC DDR3 Memory

**Date of Publication:** April 27, 2017

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

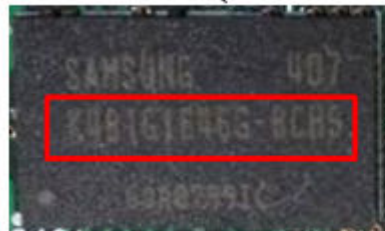
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	May 01, 2017
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*\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

## Description of Change to the Customer:

Intel is replacing the current BMC DDR3 memory chip K4B1G1646G-BCH9 (G38649-001) (end of life) with new K4B1G1646I-BCK0 (J37656-001). Intel reports validation completed with passing results. The replacement component is identical in form, fit and function.

**Current DDR3 (G38649-001)**



**New DDR3 (J37656-001)**



## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Please contact your local Intel Sales Office or Distributor if you require more information or need assistance in selecting a replacement product.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA	Pre Change PBA	Post Change PBA
E1208WTTGCNC	936188	H46989-005	H46989-006	G92187-371	G92187-372
E2224WTTGCS	936189	H46997-007	H46997-008	G92187-371	G92187-372
E2312WTTGCS	936190	H47000-002	H47000-003	G92187-371	G92187-372

## PCN Revision History:

**Date of Revision:**

April 27, 2017

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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